PK394 (v1.1) January 16, 2012

100% Material Declaration Data Sheet for XC3S1400AN FGG676 Package

Average Weight: 3.188g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die (FPGA)					**0.037750**	**1.18**
	Silicon	7440-21-3	100.00		0.037750	
Silicon Die (PROM)					**0.004100**	**0.13**
	Silicon	7440-21-3	100.00		0.004100	
Die Attach Material					**0.010100**	**0.32**
	Silver	7440-22-4	77.50		0.007830	
	Bismaleimide monomer	Trade Secret	15.00		0.001520	
	Acrylate monomer	Trade Secret	7.50		0.000760	
Die To Die Attach Film					**0.010100**	**0.32**
	Epoxy resin		12.50		0.001260	
	Phenol resin		12.50		0.001260	
	Fused silica	60676-86-0	30.00		0.003030	
	Synthetic Rubber		45.00		0.004550	
Mold Compound					**1.430100**	**44.86**
	Fused silica	60676-86-0	85.70		1.225600	
	Epoxy resin	Trade Secret	6.00		0.085810	
	Phenol resin	Trade Secret	6.00		0.085810	
	Metal Hydroxide	Trade Secret	2.00		0.028600	
	Carbon black	1333-86-4	0.30		0.004290	
Gold Wire					**0.022000**	**0.69**
	Gold (Au)	7440-57-5	99.05		0.021790	
	Palladium	7440-05-3	0.95		0.000210	
Solder Balls					**0.565470**	**17.74**
	Tin (Sn)	7440-31-5	95.50		0.540030	
	Silver (Ag)	7440-22-4	4.00		0.022620	
	Copper (Cu)	7440-50-8	0.50		0.002830	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					**1.108377**	**34.76**
	Copper (Cu)	7440-50-8	32.37		0.358800	
	Gold (Au)	7440-57-5	0.25		0.000277	
	Nickel (Ni)	7440-02-0	1.20		0.001330	
	Glass Fiber	N/A	12.50		0.138550	
	Halogen Fire Retardant	N/A	6.80		0.007537	
	Bis-maleimide triazine	N/A	33.08		0.366650	
	Epoxy	N/A	13.80		0.015296	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/21/09	1.0	Initial Xilinx release.
01/16/12	1.1	CAS# Update.

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